List of Patents and Publication

For Applicant's Information

Disclosure Statement (Use several sheets if necessary)

SERIAL NO. 10/616,086

GROUP: 2862 2858

FILING DATE: July 9, 2003

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EXAM. INITIALS	REF. DES.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	APPROPRIATE	
AD	A1	4599558	7/1986	Castellano, Jr. et al.	324	752		
AD	A2	4812756	3/1989	Curtis et al.	324	750		
Ab	A3	5485091	1/1996	Verkuil	324	455		
AD	A4	5594247	1/1997	Verkuil et al.	250	326		
Aŋ	A5	5644223	7/1997	Verkuil	324	158.1		
AD	A6	5650731	7/1997	Fung et al.	324	757		
AD	A7	5767693	6/1998	Verkuil et al.	324	767		
ΑŊ	A8	6097196	8/2000	Verkuil et al.	324	750		
AD	A9	6202029	3/2001	Verkuil et al.	702	64		
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EXAM. INITIALS	REF. DES.	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION YES/NO	
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		·····		, Title, Date, Pertinent Pa		-		
Ro	A10	Numerical Recipes in C, The Art of Scientific Computing, 2nd Ed., © Cambridge University Press 1988, 1992, p. 683.						
As	A11	Weinberg, "Tunneling of Electrons from Si into Thermally Grown SiO ₂ ," Solid-State Electronics, 1977, Vol. 20, pp. 11-18.						
Aŋ	A12	Verkuil, "Rapid Contactless Method for Measuring Fixed Oxide Charge Associated with Silicon Processing," IBM Technical Disclosure Bulletin, Vol. 24, No. 6, 1981, pp. 3048-3053.						
As	A13	"Contactless Photovoltage vs. Bias Method for Determining Flat-Band Voltage," IBM Technical Disclosure Bulletin, Vol. 32, Vol. 9A, 1990, pp. 14-17.						
A3	A14	"Contactless Electrical Equivalent Oxide Thickness Measurement," IBM Technical Disclosure Bulletin, Vol. 29, No. 10, 1987, pp. 4622-4623.						

AD6	
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2/15/2005

EXAMINER:

DATE CONSIDERED:

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the patent owner.